Dual PNP Bias Resistor Transistors R1 = 2.2 kΩ, R2 = ∞ kΩ

PNP Transistors with Monolithic Bias Resistor Network

This series of digital transistors is designed to replace a single device and its external resistor bias network. The Bias Resistor Transistor (BRT) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base-emitter resistor. The BRT eliminates these individual components by integrating them into a single device. The use of a BRT can reduce both system cost and board space.

Features

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- This Device is Pb-Free, Halogen Free/BFR Free and is RoHS Compliant

MAXIMUM RATINGS

 $(T_A = 25^{\circ}C, common for Q_1 and Q_2, unless otherwise noted)$

Rating	Symbol	Max	Unit
Collector-Base Voltage	V _{CBO}	50	Vdc
Collector-Emitter Voltage	V _{CEO}	50	Vdc
Collector Current - Continuous	I _C	100	mAdc
Input Forward Voltage	V _{IN(fwd)}	12	Vdc
Input Reverse Voltage	V _{IN(rev)}	5	Vdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ORDERING INFORMATION

Device	Package	Shipping [†]
NSBA123TDP6T5G	SOT-963	8,000/Tape & Reel

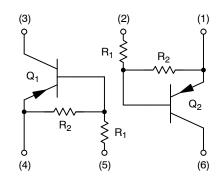
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



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PIN CONNECTIONS



MARKING DIAGRAM



SOT-963 CASE 527AD



L = Specific Device Code M = Date Code*

*Date Code orientation may vary depending upon manufacturing location.

THERMAL CHARACTERISTICS

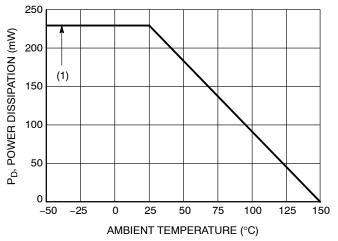
Characteristic		Symbol	Max	Unit
NSBA123TDP6 (SOT-963) ONE JUNCTION HEA	TED			
		P _D	231 269 1.9 2.2	MW mW/°C
Thermal Resistance, Junction to Ambient (Note 1) (Note 2)		$R_{ heta JA}$	540 464	°C/W
NSBA123TDP6 (SOT-963) BOTH JUNCTION HE	ATED (Note 3)			
		P _D	339 408 2.7 3.3	MW mW/°C
Thermal Resistance, Junction to Ambient (Note 1) (Note 2)		$R_{ hetaJA}$	369 306	°C/W
Junction and Storage Temperature Range		T _J , T _{stq}	-55 to +150	°C

FR-4 @ 100 mm², 1 oz. copper traces, still air.
 FR-4 @ 500 mm², 1 oz. copper traces, still air.
 Both junction heated values assume total power is sum of two equally powered channels.

ELECTRICAL CHARACTERISTICS (T_A = 25°C, common for Q₁ and Q₂, unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS			1	1	•
Collector-Base Cutoff Current $(V_{CB} = 50 \text{ V}, I_E = 0)$	Ісво	-	-	100	nAdc
Collector-Emitter Cutoff Current (V _{CE} = 50 V, I _B = 0)	I _{CEO}	-	-	500	nAdc
Emitter-Base Cutoff Current (V _{EB} = 6.0 V, I _C = 0)	I _{EBO}	-	-	4.0	mAdc
Collector-Base Breakdown Voltage (I _C = 10 μA, I _E = 0)	V _{(BR)CBO}	50	-	-	Vdc
Collector-Emitter Breakdown Voltage (Note 4) (I _C = 2.0 mA, I _B = 0)	V _{(BR)CEO}	50	-	-	Vdc
ON CHARACTERISTICS					
DC Current Gain (Note 4) (I _C = 5.0 mA, V _{CE} = 10 V)	h _{FE}	160	350	-	
Collector-Emitter Saturation Voltage (Note 4) $(I_C = 10 \text{ mA}, I_B = 0.3 \text{ mA})$	V _{CE(sat)}	-	-	0.25	V
Input Voltage (Off) ($V_{CE} = 5.0 \text{ V}, I_C = 100 \mu\text{A}$)	V _{i(off)}	-	0.6	-	Vdc
Input Voltage (On) (V _{CE} = 0.2 V, I _C = 10 mA)	V _{i(on)}	-	0.9	-	Vdc
Output Voltage (On) ($V_{CC} = 5.0 \text{ V}, V_B = 2.5 \text{ V}, R_L = 1.0 \text{ k}\Omega$)	V _{OL}	-	-	0.2	Vdc
Output Voltage (Off) (V _{CC} = 5.0 V, V _B = 0.5 V, R _L = 1.0 k Ω)	V _{OH}	4.9	-	-	Vdc
Input Resistor	R1	1.5	2.2	2.9	kΩ
Resistor Ratio	R ₁ /R ₂	_	-	_	

^{4.} Pulsed Condition: Pulse Width = 300 ms, Duty Cycle ≤ 2%.



(1) SOT-963; 100 mm², 1 oz. Copper Trace

Figure 1. Derating Curve

TYPICAL CHARACTERISTICS NSBA123TDP6

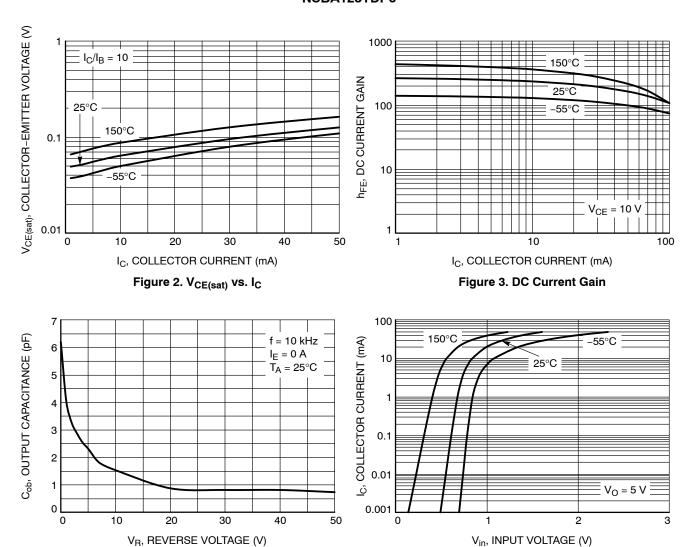


Figure 4. Output Capacitance

Figure 5. Output Current vs. Input Voltage

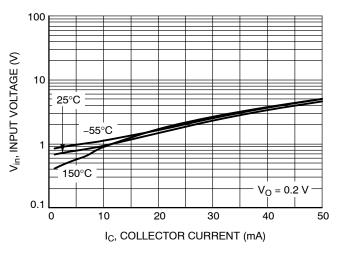


Figure 6. Input Voltage vs. Output Current

MECHANICAL CASE OUTLINE

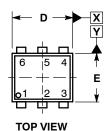


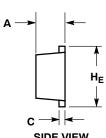


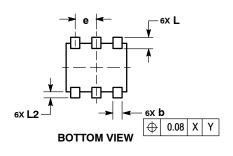
SOT-963 CASE 527AD-01 **ISSUE E**

DATE 09 FEB 2010

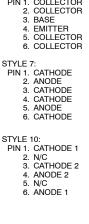




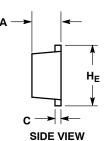




STYLE 1: PIN 1. EMITTER 1 2. BASE 1 3. COLLECTOR 2 4. EMITTER 2 5. BASE 2 6. COLLECTOR 1
STYLE 4: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR
STYLE 7: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. ANODE 6. CATHODE



STYLE 2: PIN 1. EMITTER 1 2. EMITTER2 3. BASE 2 4. COLLECTOR 2 5. BASE 1 6. COLLECTOR 1	STYLE 3: PIN 1. CATHODE 1 2. CATHODE 1 3. ANODE/ANODE 2 4. CATHODE 2 5. CATHODE 2 6. ANODE/ANODE 1
STYLE 5:	STYLE 6:
PIN 1. CATHODE 2. CATHODE	PIN 1. CATHODE 2. ANODE
3. ANODE	3. CATHODE
4. ANODE	4. CATHODE
5. CATHODE 6. CATHODE	5. CATHODE 6. CATHODE
STYLE 8:	STYLE 9:
PIN 1. DRAIN	PIN 1. SOURCE 1
2. DRAIN 3. GATE	2. GATE 1 3. DRAIN 2
4. SOURCE	4. SOURCE 2
5. DRAIN	5. GATE 2
6. DRAIN	6. DRAIN 1



NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- DIMENSIONING AND TOLEHANCING PER ASM Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.34	0.37	0.40	
b	0.10	0.15	0.20	
С	0.07	0.12	0.17	
D	0.95	1.00	1.05	
E	0.75	0.80	0.85	
е	0.35 BSC			
HE	0.95	1.00	1.05	
L	0.19 REF			
L2	0.05	0.10	0.15	

GENERIC MARKING DIAGRAM*

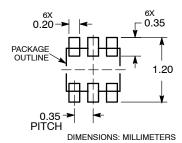


= Specific Device Code = Month Code Μ

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT



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